



**THE DATASHEET OF
ILD2-X001**





Option Information

Optocoupler lead-bend configurations are available as options. In addition, partial discharge testing as per VDE / IEC is also available as an option.

See the order information section in the data sheet to determine if and which options are available to a specific product. Contact the Vishay sales office for other option configurations.

The options are:

- Option 1 VDE option
- Option 6 400 mil (10.16 mm) lead spread DIP configuration
- Option 7 Surface mount, gull wing DIP configuration with standoff
- Option 8 Surface mount, gull wing DIP configuration with increased clearance
- Option 9 Surface mount, gull wing DIP configuration

ORDERING OPTIONS

A specific option or combination of options can be ordered by add the options definition field following the base part

number and CTR range (if applicable) as presented in the following example:



Examples:
 CNY17F-2X017T
 4N35-X016
 SFH615-3X001
 VO615A-9X007T

Note
⁽¹⁾ Used on selected products, consult data sheet for details

18482

This field is always 4 characters long and commences with the character X. In the case of surface mounted products in tape and reel format, the tape and reel option character "T" will follow this field.

The possible combinations for these fields ⁽¹⁾ are:
X001, X006, X007, X008, X009, X001T ⁽²⁾, X007T, X008T, X009T, X016, X017, X018, X019, X017T, X018T, X019T

Notes

- ⁽¹⁾ Not all options are available for all product types.
- ⁽²⁾ The X001T option is only available on products that are available on the following SMD products SFH6106, SFH6156, SFH6186, SFH6206, and SFH6286 series, e.g. SFH6106-3X001T .

OPTION 1 OPTOCOUPERS FOR SAFE ELECTRICAL INSULATION PER DIN EN 60747-5-5 (VDE 0884) ⁽¹⁾

The optocoupler listed are suitable for safe electrical insulation only within the safety maximum ratings. Compliance with the safety maximum ratings must be ensured by protective circuits.

The partial discharge measurement ensures that no partial discharge occurs during operation at maximum permissible operating insulation voltage (V_{IORM}). Permanent partial discharge affects the insulating materials and can result in a high voltage breakdown.

It is recommended that tests with the insulation test voltage (V_{ISOL}) should not be made, otherwise partial discharge may occur impairing the insulation characteristics. Thus partial discharges also may occur at the maximum permissible operating insulation voltage.

The insulation test per DIN EN 60747-5-5 (VDE 0884) is carried out after all the other tests



Fig. 1 - Time Voltage Diagram per DIN EN 60747-5-5

| DESCRIPTION | SYMBOL | SYSTEM 1 | | | UNIT |
|--|-----------------|--------------|-------------|-------------|-------------|
| | | DIP4 | DIP8 | DIP16 | |
| | | SFH610A-.. | ILCT6 | ILQ1/2/5/74 | |
| | | SFH615A-.. | ILD1/2/5/74 | ILQ30/31/55 | |
| | | SFH615AA-.. | ILD30/31/55 | ILQ32 | |
| | | SFH615AGB-.. | ILD32 | ILQ66-.. | |
| | | SFH615AGR-.. | ILD66-.. | ILQ615-.. | |
| | | SFH617A-.. | ILD250/1/2 | ILQ620-.. | |
| | | SFH618A-.. | ILD255 | ILQ620GB-.. | |
| | | SFH620A-.. | ILD621GB-.. | ILQ621-.. | |
| | | SFH620AA-.. | ILD621-.. | ILQ621GB-.. | |
| | | SFH620AGB-.. | ILD621GB-.. | | |
| | | SFH628A-.. | ILD755-.. | | |
| | | SFH6106-.. | ILD766-.. | | |
| | | SFH6116-.. | MCT6 | | |
| | | SFH6156-.. | | | |
| | | SFH6186-.. | | | |
| | | SFH6206-.. | | | |
| | | SFH6286-.. | | | |
| Installation category (DIN VDE 0110) | | | | | |
| For rated line voltages $\leq 300 V_{RMS}$ | | | I to IV | | |
| For rated line voltages $\leq 600 V_{RMS}$ | | | I to IV | | |
| For rated line voltages $\leq 1000 V_{RMS}$ | | | | | |
| IEC climatic category (DIN IEC 60068 Part 1/9.80) | | | 55/100/21 | | |
| Pollution degree (DIN VDE 0110 Part 1/1.89) | | | 2 | | |
| Maximum operation insulating voltage ⁽¹⁾ | V_{IORM} | | 890 | | V_{peak} |
| Test voltage input/output, procedure b ⁽¹⁾ $V_{Pr} = 1.875 \times V_{IORM}$, routine 100 % test, $t_p = 1$ s, partial discharge < 5 pC | V_{Pr} | | 1669 | | V_{peak} |
| Test voltage input/output, procedure a ⁽¹⁾ $V_{Pr} = 1.6 \times V_{IORM}$, type and sampling test $t_p = 60$ s, partial discharge < 5 pC | V_{Pr} | | 1424 | | V_{peak} |
| Maximum permissible overvoltage (transient overvoltage) | V_{IOTM} | | 10 000 | | V_{peak} |
| Partial discharge test voltage ⁽¹⁾ | $V_{INITIAL}$ | | 8000 | | V_{peak} |
| Safety maximum ratings (maximum permissible ratings in case of a fault, also refer to d diagram) | | | | | |
| Package temperature | T_{Si} | | 175 | | $^{\circ}C$ |
| Current (input current I_F , $P_{Si} = 0$, $T_A = 25$ $^{\circ}C$) | I_{Si} | | 275 | | mA |
| Derating with higher ambient temperature | ΔI_{Si} | | -1.83 | | mA/K |
| Power (output or total power dissipation, $T_A = 25$ $^{\circ}C$) | P_{Si} | | 400 | | mW |
| Derating with higher ambient temperature | ΔP_{Si} | | -2.67 | | mW/K |
| Insulation resistance at T_{Si} $V_{IO} = 500$ V | R_{IS} | | $> 10^9$ | | W |



| DESCRIPTION | SYMBOL | SYSTEM 2 | | | UNIT |
|--|-----------------|------------------|------------|------------------|-------------|
| | | 4N25/26/27/28 | IL250 | MCT5210 | |
| | | 4N35/36/37/38/39 | IL251 | MCT5211 | |
| | | 4N32/33 | IL252 | SFH600-.. | |
| | | CNY17-.. | IL255-.. | SFH601-.. | |
| | | CNY17F-.. | IL400 | SFH608-.. | |
| | | H11A-.. | IL755-.. | SFH640-.. | |
| | | H11AA1-.. | IL755B-.. | MOC8050 | |
| | | H11B-.. | IL766-.. | IL56B-.. | |
| | | H11B1-.. | IL766B-.. | MOC8021 | |
| | | H11C-.. | MCA230/231 | MOC8112 | |
| | | H11D-.. | MCA255 | MOC8102/03/04/05 | |
| | | IL1/2/5/74 | MCT2/2E | VO610A... | |
| | | IL2B-.. | MCT270/271 | VO615A... | |
| | | IL30/31/55 | MCT272 | VO617A... | |
| | | IL55B-.. | MCT273/274 | VO618A... | |
| | | IL66-.. | MCT275 | VO615C... | |
| | | IL66B-.. | MCT276/277 | VO617C... | |
| | | IL201/202/203 | | | |
| Installation category (DIN VDE 0110) | | | | | |
| For rated line voltages $\leq 300 V_{RMS}$ | | | I to IV | | |
| For rated line voltages $\leq 600 V_{RMS}$ | | | I to IV | | |
| For rated line voltages $\leq 1000 V_{RMS}$ | | | | | |
| IEC climatic category (DIN IEC 60068 Part 1/9.80) | | | 55/100/21 | | |
| Pollution degree (DIN VDE 0110 Part 1/1.89) | | | 2 | | |
| Maximum operation insulating voltage ⁽¹⁾ | V_{IORM} | | 890 | | V_{peak} |
| Test voltage input/output, procedure b ⁽¹⁾ $V_{Pr} = 1.875 \times V_{IORM}$, routine 100 % test, $t_p = 1$ s, partial discharge < 5 pC | V_{Pr} | | 1669 | | V_{peak} |
| Test voltage input/output, procedure a ⁽¹⁾ $V_{Pr} = 1.6 \times V_{IORM}$, type and sampling test $t_p = 60$ s, partial discharge < 5 pC | V_{Pr} | | 1424 | | V_{peak} |
| Maximum permissible overvoltage (transient overvoltage) | V_{IOTM} | | 8000 | | V_{peak} |
| Partial discharge test voltage ⁽¹⁾ | $V_{INITIAL}$ | | 8000 | | V_{peak} |
| Safety maximum ratings (maximum permissible ratings in case of a fault, also refer to diagram) | | | | | |
| Package temperature | T_{Si} | | 175 | | $^{\circ}C$ |
| Current (input current I_F , $P_{Si} = 0$, $T_A = 25$ $^{\circ}C$) | I_{Si} | | 400 | | mA |
| Derating with higher ambient temperature | $D I_{Si}$ | | -2.67 | | mA/K |
| Power (output or total power dissipation, $T_A = 25$ $^{\circ}C$) | P_{Si} | | 700 | | mW |
| Derating with higher ambient temperature | ΔP_{Si} | | -4.67 | | mW/K |
| Insulation resistance at T_{Si} $V_{I/O} = 500$ V | R_{IS} | | $> 10^9$ | | W |



| DESCRIPTION | SYMBOL | SYSTEM 4 ⁽²⁾ | SYSTEM 5 | SYSTEM 7 | UNIT |
|--|-----------------|-------------------------|-----------|-----------|-------------|
| | | IL410 | 6N135 | IL300 | |
| | | IL420 | 6N136 | IL300E | |
| | | IL4116 | SFH6135 | IL300F | |
| | | IL4117 | SFH6136 | IL300EF | |
| | | IL4118 | 6N138 | IL300DEFG | |
| | | IL4216 | SFH6138 | | |
| | | IL4217 | SFH6139 | | |
| | | IL4218 | 6N139 | | |
| | | | SFH6345 | | |
| | | | 6N137... | | |
| | | | VO2601... | | |
| | | | VO2611... | | |
| | | | VO2630... | | |
| | | | VO2631... | | |
| | | | VO4661... | | |
| Installation category (DIN VDE 0110) | | | | | |
| For rated line voltages $\leq 300 V_{RMS}$ | | I to IV | I to IV | I to IV | |
| For rated line voltages $\leq 600 V_{RMS}$ | | I to III | I to IV | I to IV | |
| For rated line voltages $\leq 1000 V_{RMS}$ | | | | | |
| IEC climatic category (DIN IEC 60068 Part 1/9.80) | | 55/100/21 | 55/100/21 | 55/100/21 | |
| Pollution degree (DIN VDE 0110 Part 1/1.89) | | 2 | 2 | 2 | |
| Maximum operation insulating voltage ⁽¹⁾ | V_{IORM} | 890 | 890 | 890 | V_{peak} |
| Test voltage input/output, procedure b ⁽¹⁾ $V_{Pr} = 1.875 \times V_{IORM}$, routine 100 % test, $t_p = 1$ s, partial discharge < 5 pC | V_{Pr} | 1669 | 1669 | 1669 | V_{peak} |
| Test voltage input/output, procedure a ⁽¹⁾ $V_{Pr} = 1.6 \times V_{IORM}$, type and sampling Test $t_p = 60$ s, partial discharge < 5 pC | V_{Pr} | 1424 | 1424 | 1424 | V_{peak} |
| Maximum permissible overvoltage (transient overvoltage) | V_{IOTM} | 8000 | 8000 | 8000 | V_{peak} |
| Partial discharge test voltage ⁽¹⁾ | $V_{INITIAL}$ | 8000 | 8000 | 8000 | V_{peak} |
| Safety maximum ratings (maximum permissible ratings in case of a fault, also refer to diagram) | | | | | |
| Package temperature | T_{Si} | 175 | 175 | 165 | $^{\circ}C$ |
| Current (input current I_F , $P_{Si} = 0$, $T_A = 25$ $^{\circ}C$) | I_{Si} | 250 | 300 | 235 | mA |
| Derating with higher ambient temperature | DI_{Si} | -1.65 | -2 | -1.57 | mA/K |
| Power (output or total power dissipation, $T_A = 25$ $^{\circ}C$) | P_{Si} | 500 | 500 | 465 | mW |
| Derating with higher ambient temperature | ΔP_{Si} | -3.33 | -3.33 | -3.1 | mW/K |
| Insulation resistance at T_{Si} $V_{I/O} = 500$ V | R_{IS} | $> 10^9$ | $> 10^9$ | $> 10^9$ | W |

Notes

All voltages referred to are peak values except otherwise specified.

⁽¹⁾ See time-test voltage diagram

⁽²⁾ In preparation

Testing input / output voltage requires all input pins and all output pins to be shorted

Option 1: Tested per DIN EN 60747-5-2 (VDE 0884) / DIN EN 60747-5-5 (pending)

Option 6: Wide lead spacing (10.16 mm creepage / clearance distances > 8 mm)

Option 7: Surface mount leads (creepage / clearance distances > 8 mm)

Option 8: Surface mount leads

Option 9: Surface mount leads

See CECC 00802, edition 1, for soldering conditions for SMT devices (option 7 and 9).

“-..” means dash selections

OPTION 6 DIP OPTOCOUPERS WITH 0.4" (10.16 mm) LEAD SPREAD

The leads of the optocouplers are bent according to a spacing of 0.4" (10.16 mm). Dimensions deviating from the standard type are:

- Lead spacing 10.16 mm (0.4")
- Creepage distance > 8 mm
- Clearance > 8 mm

This version additionally complies with the following standards:

- IEC 60950 DIN VDE 0805/05 90 (System 2 and 3 only)
Reinforced insulation up to an operating voltage of 400

V_{RMS} or DC



Clearance-creepage distance = 8 mm min.
See standard version for pin configuration

OPTION 7 LEAD BENDS FOR SURFACE MOUNT OPTOCOUPERS

These optocouplers are suitable for surface mounting. Dimensions deviating from the standard type are:

- Creepage distance > 8 mm
- Clearance distance > 8 mm

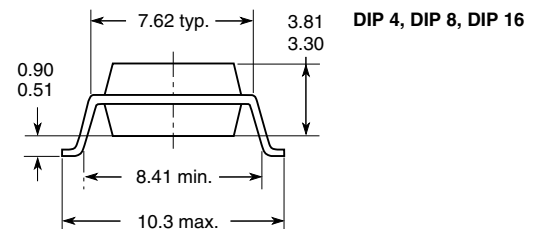
This version additionally complies with the following standards:

- IEC 60950 DIN VDE 0805/05 90 (system 2 and 3 only)
Reinforced insulation up to an operating voltage of 400 V_{RMS} or DC

During the soldering process, the package should not be wetted with tin-lead solder to prevent the impairment of the isolation features. Apart from iron soldering, only reflow soldering methods (vapor phase, infrared and hot gas) are permissible.

Permissible soldering conditions for SMD bending options: please see reflow soldering profile.

The soldering process may be repeated two times at the most. Attention must be paid to the cooling down of the device to 25 °C between the soldering processes.



Clearance and creepage distances must be considered for the solder pad design.

Clearance-creepage distance = 8 mm min.

See standard version for pin configuration.

OPTION 8 LEAD BENDS FOR SURFACE MOUNT OPTOCOUPLEDERS

These optocouplers are suitable for surface mounting. Dimensions deviating from the standard type are:

Creepage distance > 8 mm

Clearance distance > 8 mm

This version additionally complies with the following standards:

- IEC 60950 DIN VDE 0805/05 90 (system 2 and 3 only)
Reinforced insulation up to an operating voltage of 400 V_{RMS} or DC

During the soldering process, the package should not be wetted with tin-lead solder to prevent the impairment of the isolation features. Apart from iron soldering, only reflow soldering methods (vapor phase, infrared and hot gas) are permissible.

Permissible soldering conditions for SMD bending options: please see reflow soldering profile.

The soldering process may be repeated two times at the most. Attention must be paid to the cooling down of the device to 25 °C between the soldering processes.



17932-1

Clearance and creepage distances must be considered for the solder pad design.

Clearance-creepage distance = 8 mm min.

See standard version for pin configuration.

OPTION 9 LEAD BENDS FOR SURFACE MOUNT OPTOCOUPLEDERS

During the soldering process, the package should not be wetted with tin-lead solder to prevent the impairment of the isolation features. Apart from iron soldering, only reflow soldering methods (vapor phase, infrared and hot gas) are permissible.

Permissible soldering conditions for SMD bending options: please see reflow soldering profile.

The soldering process may be repeated two times at the most. Attention must be paid to the cooling down of the device to 25 °C between the soldering processes.



17933-1



MARKINGS

Product marking is defined in the datasheets. In the cases where marking is not defined in the datasheet, the following table defines the option information that is marked on the product.

| OPTION TYPE | MARKING |
|-------------|-------------------------|
| X001, X001T | X001, X1 ⁽¹⁾ |
| X006 | No mark |
| X007, X007T | X007 |
| X008, X008T | X008 |
| X009, X009T | No mark |
| X016 | X001 |
| X017, X017T | X017 |
| X018, X018T | X018 |
| X019, X019T | X001 |

Note

⁽¹⁾ X1 is used on the SOP and SOIC-8 where there are space constraints.

Note

The information in this document provides generic information on options but for specific information on a product the appropriate product datasheet should be used.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View ILD2-X001 on WIN SOURCE](#)

 [Vishay Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management